current status

new PCB designs

SCROD revA2

IRS2_DC revB2

carrier0 revB

new heatsink concept

bench testing

still too hot!
next steps

- design new carrier 1, 2, 3
  - with new thermal structures for heatsinks
  - with different amplifier options
- new HV circuit idea being developed at Indiana
  - using high-voltage bipolar transistors
- rethink front-back, front-front boards
  - to eliminate 2mm connectors between boards